

Automotive Process Change Notification

Date: June 23, 2014

PCN Reference: AU-14-126A, Qualification of Vanguard International Semiconductor Corporation (VIS) for PCube IPS Technology

Product Reference: Automotive Intelligent Power Switch (IPS) Products

To Our Valued Customer:

We thank you for your use of International Rectifier (IR) semiconductor products. Our commitment to customer satisfaction and continuous improvement is demonstrated by our change plans to enhance capacity, quality and reliability. We would like to express our sincere appreciation for your cooperation regarding the following changes, and IR will work closely with you to support your requirements during this transition.

Type of Change Notification:

- Wafer fab site
- Test site
- Wafer diameter
- Top protective layer material (Gen10.7 MOSFETs only)
- Marking appearance

Description of Change:

PCube IPS products currently manufactured and wafer-level tested in the IR Newport, South Wales UK (Fab 10) six inch facility will be transferred to the VIS Hsinchu, Taiwan (Fab 2) eight inch wafer fab and subcontractor facilities.

Concurrent with this change, Gen10.7 MOSFETs used in IPS copack products, currently manufactured in the IR Newport, South Wales UK (Fab 10) six inch facility will be transferred to the VIS Hsinchu, Taiwan (Fab 2) facility.

A passivation layer will be added to all VIS Gen10.7 unpassivated MOSFETs in order to improve robustness and reliability.

Reason for the Change:

As part of a manufacturing consolidation plan announced in 2012, International Rectifier indicated that it would be closing the IR Fab 10 facility and transferring the production capability for certain parts to foundries.

The top marking of the part will be changed to be consistent with standard AU parts.

Effective Date:

December 23, 2014

Impact of Change:

No changes to form, fit, or function. The package outline remains the same. Datasheet specifications will not be changed. The location for assembly and final test will not change. If applicable, the copack MOSFET die will remain the same.

Products Affected:

IR Part Number	Package	Copack (FET)
AUIR3316STRL	D ² Pak	Gen7
AUIR3316S	D ² Pak	Gen7
AUIR3320S	D ² Pak	Gen10.7
AUIR3320STRL	D ² Pak	Gen10.7
AUIPS7141RTRL	D-Pak	No
AUIPS7141R	D-Pak	No
AUIPS7121R	D-Pak	No
AUIPS7121RTRL	D-Pak	No
AUIPS1021R	D-Pak	No
AUIPS1021S	D ² Pak	No
AUIPS1021RTRL	D-Pak	No
AUIPS1021STRL	D ² Pak	No
AUIPS7091STRL	D ² Pak	No
AUIPS7091GTR	SO-8	No
AUIPS7091S	D ² Pak	No

Method of Identifying Changed Product:

Wafer fab origins will not be distinguished through the external part making or shipping labels; however, IR internal systems will be able to trace the site of the wafer lots used to produce the final product.

Qualification and Supporting Data Availability:

Available now.

Sample Availability:

Available now.

Contact Information:

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